



Film Capacitors

Metallized Polypropylene Film Capacitors (MKP)

Series/Type: B32671L8

Date: December 2012

Typical applications

- Electronic ballasts (resonant circuits)
- SMPS
- High-frequency AC loads
- Pulse circuits

Climatic

- Max. operating temperature: +125 °C
- Climatic category (IEC 60068-1): 55/110/56

Construction

- Dielectric: polypropylene (PP)
- Wound capacitor technology
- Plastic case (UL 94 V-0)
- Epoxy resin sealing

Features

- Very high AC voltages for all frequency ranges
- Very small dimensions
- High peak voltage for short time periods
- High peak current
- High pulse withstand capability
- RoHS-compatible
- Halogen-free capacitors available on request

Terminals

- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

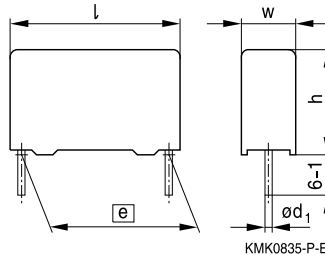
Marking

- Manufacturer's logo
- Lot number, series number
- Rated capacitance (coded)
- Capacitance Tolerance (code letter)
- Rated AC voltage
- Date of manufacture (coded)

Delivery mode

- Bulk (untaped)

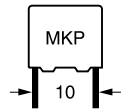
Dimensional drawing



Dimensions in mm

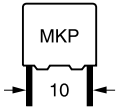
Lead spacing	Lead diameter d_1
$e \pm 0.4$	
10	0.6

B32671L8
High V AC, high temperature (wound)



Overview of available types

Lead spacing	10 mm
Type	B32671L8
Page	4
V_{RMS} (V AC)	700
V_R (V DC)	2000
C_R (nF)	
1.0	
1.2	
1.5	
2.0	
2.2	
2.7	
3.3	
3.9	
4.7	


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Ordering codes and packing units

V_{RMS} f £1 kHz V AC	V_R V DC	C_R nF	Max. dimensions w' h' l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./ MOQ	Untaped pcs./ MOQ
700	2000	1.0	4.0 ´ 9.0 ´ 13.0	B32671L8102+***	4000	6800	4000
		1.2	4.0 ´ 9.0 ´ 13.0	B32671L8122+***	4000	6800	4000
		1.5	4.0 ´ 9.0 ´ 13.0	B32671L8152+***	4000	6800	4000
		2.0	5.0 ´ 11.0 ´ 13.0	B32671L8202+***	3320	5200	4000
		2.2	5.0 ´ 11.0 ´ 13.0	B32671L8222+***	3320	5200	4000
		2.7	5.0 ´ 11.0 ´ 13.0	B32671L8272+***	3320	5200	4000
		3.3	5.0 ´ 11.0 ´ 13.0	B32671L8332+***	3320	5200	4000
		3.9	6.0 ´ 12.0 ´ 13.0	B32671L8392+***	2720	4400	4000
		4.7	6.0 ´ 12.0 ´ 13.0	B32671L8472+***	2720	4400	4000

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series, intermediate capacitance values and closer tolerances on request.

Composition of ordering code

+ = Capacitance tolerance code:

K = ±10%

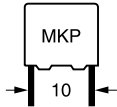
J = ±5%

*** = Packaging code:

289 = Ammo pack

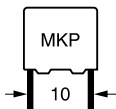
189 = Reel

000 = Untaped (lead length 6 ± 1 mm)



Technical data

Operating temperature range	Max. operating temperature $T_{op,max}$			+125 °C	
	Upper category temperature T_{max}			+110 °C	
	Lower category temperature T_{min}			55 °C	
	Rated temperature T_R			+85 °C	
Dissipation factor tan d (in 10 ⁻³) at 20 °C (upper limit values)	at	£27 nF	27 nF< C_R £0.1 nF	0.1 nF < C_R £1 nF	>1 nF
	1 kHz	0.8	0.8	0.8	0.8
	10 kHz	1.0	1.0	1.0	
	100 kHz	2.0	3.0		
Insulation resistance R_{ins} at 20 °C, rel. humidity £ 65% (minimum as-delivered values)	> 100 GW(500 V, 1 min)				
DC test voltage	1.6 V_R , 2 s				
Category voltage V_C (continuous operation with V_{DC} or V_{AC} at f £ 1 kHz)	T_A (°C)	DC voltage derating		AC voltage derating	
	T_A £ 85	$V_C = V_R$		$V_{C,RMS} = V_{RMS}$	
	85< T_A £110	$V_C = V_R (165 - T_A)/80$		$V_{C,RMS}=V_{RMS} (165 - T_A)/80$	
Operating voltage V_{op} for short operating periods (V_{DC} or V_{AC} at f £ 1 kHz)	T_A (°C)	DC voltage (max. hours)		AC voltage (max. hours)	
	T_A £ 100	$V_{op} = 1.25 V_C$ (2000 h)		$V_{op} = 1.0 V_{C,RMS}$ (2000 h)	
	100< T_A £125	$V_{op} = 1.25 V_C$ (1000 h)		$V_{op} = 1.0 V_{C,RMS}$ (1000 h)	
Damp heat test	56 days/40 °C/93% relative humidity				
Limit values after damp heat test	Capacitance change $\Delta C/C$			£ 2%	
	Dissipation factor change $\Delta \tan d$			£ 1.0 10^{-3} (at 1 kHz)	
	Insulation resistance R_{ins}			³ 50 GW	
Endurance test conditions	+85 °C / 2500 V DC / 2000 h +85 °C / 880 V AC / 2000 h +110 °C / 1700 V DC / 2000 h +110 °C / 610 V AC / 2000 h				
Reliability:					
Failure rate I	1 fit (£1 10^{-9} /h) at 0.5 V_R , 40 °C				
Service life t_{SL}	200 000 h at 1.0 V_R , 85 °C				
	For conversion to other operating conditions and temperatures, refer to chapter "Quality, 2 Reliability".				
Failure criteria:					
Total failure	Short circuit or open circuit				
Failure due to variation of parameters	Capacitance change $\Delta C/C$			> 10%	
	Dissipation factor tan d			> 4 upper limit values	
	Insulation resistance R_{ins}			< 1500 MW	



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High V AC, high temperature (wound)

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/ms.

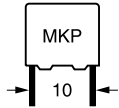
"k₀" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V²/ms.

Note:

The values of dV/dt and k₀ provided below must not be exceeded in order to avoid damaging the capacitor.

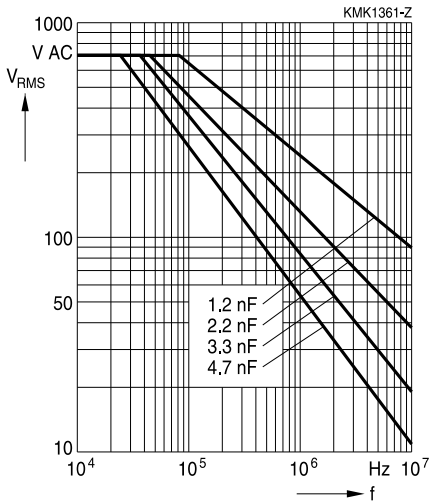
dV/dt and k₀ values

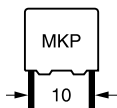
Lead spacing	10 mm	
Type	B32671L8	
V _{RMS} (V AC)	700	
V _R (V DC)	2000	
C _R (nF)	dV/dt in V/ms	k ₀ in V ² /ms
1.0	11000	25000000
1.2	10000	23000000
1.5	9500	22500000
2.0	9100	22100000
2.2	9000	22000000
2.7	8600	21500000
3.3	8500	21000000
3.9	8200	20900000
4.7	8000	20800000



Preliminary permissible AC voltage V_{RMS} versus frequency f (for sinusoidal waveforms $T_A \leq 100^\circ\text{C}$)

For $T_A > 100^\circ\text{C}$, please refer to "General technical information", section 3.2.3.




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Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

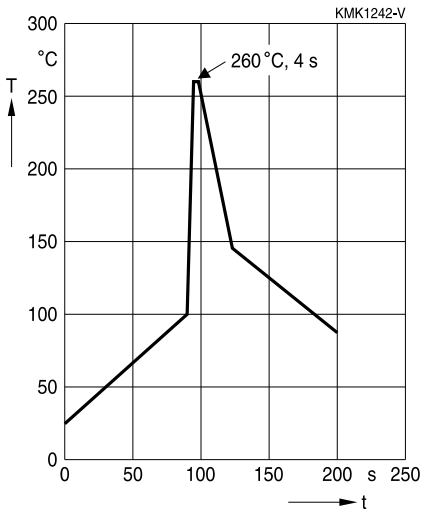
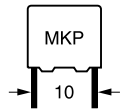
Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/- 0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥ 90%, free-flowing solder

1.2 Resistance to soldering heat

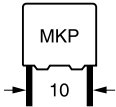
Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A.

Conditions:

Series	Solder bath temperature	Soldering time
MKT boxed (except 2.5 ´ 6.5 ´ 7.2 mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP		
MKP (lead spacing > 7.5 mm)		
MKT boxed (case 2.5 ´ 6.5 ´ 7.2 mm)		5 ±1 s
MKP (lead spacing ≤ 7.5 mm) MKT uncoated (lead spacing ≤ 10 mm) insulated (B32559)		< 4 s recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



Immersion depth	2.0 +0/- 0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
DC/C ₀	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification



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High V AC, high temperature (wound)

1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

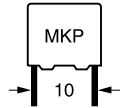
EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
MKP/MFP 110 °C
MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≥ 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

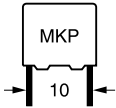


Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

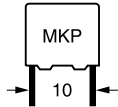
Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



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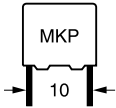
High V AC, high temperature (wound)

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"



Symbols and terms

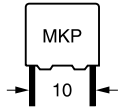
Symbol	English	German
a	Heat transfer coefficient	Wärmeübergangszahl
a_C	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
b_C	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
DC	Absolute capacitance change	Absolute Kapazitätsänderung
DC/C	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
DC/ C_R	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Dt	Time interval	Zeitintervall
DT	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
Dtan d	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
DV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
DV/Dt	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f_1	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f_2	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f_r	Resonant frequency	Resonanzfrequenz
F_D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I_C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



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Symbol	English	German
I_{RMS}	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
i_z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
L_S	Series inductance	Serieninduktivität
I	Failure rate	Ausfallrate
I_0	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
I_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
r	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
R_i	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_p	Parallel resistance	Parallelwiderstand
R_S	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtest)
t	Time	Zeit
T	Temperature	Temperatur
t	Time constant	Zeitkonstante
$\tan \delta$	Dissipation factor	Verlustfaktor
$\tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$\tan \delta_p$	Parallel component of dissipation factor	Parallelanteil des Verlustfaktors
$\tan \delta_S$	Series component of dissipation factor	Serienanteil des Verlustfaktors
T_A	Ambient temperature	Umgebungstemperatur
T_{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t_{OL}	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
T_{op}	Operating temperature	Betriebstemperatur
T_R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t_{SL}	Reference service life	Referenz-Lebensdauer
V_{AC}	AC voltage	Wechselspannung



Symbol	English	German
V_C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_i	Input voltage	Eingangsspannung
V_o	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
$\hat{V}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
e	Lead spacing	Rastermaß

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